

**30V N-Channel Enhancement Mode MOSFET****Description**

The PECN3404A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and high density cell Design for ultra low on-resistance. This device is suitable for use as a load switch or in PWM applications.

**General Features**

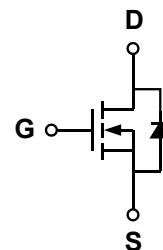
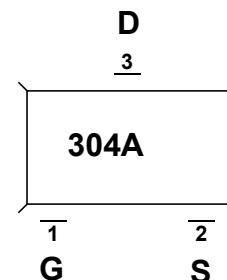
- ◆  $V_{DS} = 30V$ ,  $I_D = 6A$   
 $R_{DS(ON)}(\text{Typ.}) = 16m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(ON)}(\text{Typ.}) = 21m\Omega$  @  $V_{GS} = 4.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

**Application**

- ◆ PWM applications
- ◆ Load switch

**Package**

SOT-23-3L

**Schematic diagram****Marking and pin assignment**SOT-23-3L  
(TOP VIEW)PECN—Natlinear  
Power 304A—**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN3404AM R-G	-55°C to +150°C	SOT-23-3L	3000

**Absolute Maximum Ratings (TA=25°C unless otherwise noted)**

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	30	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current  $T_A = 25^\circ C$	$I_D$	6	A
		5	A
Pulsed Drain Current	$I_{DM}$	24	A
Avalanche energy( L=0.1mH)	$E_{AS}, E_{AR}$	32	mJ
Maximum power dissipation	$P_D$	1.4	W
Operating junction Temperature range	$T_j$	-55—150	°C

**Electrical Characteristics** (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-body leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
<b>ON Characteristics</b>						
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.8	1.35	1.9	V
Drain-source on-state resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =6A	-	16	20	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A		21	26	
Forward transconductance	g <sub>f</sub>	V <sub>GS</sub> =5V, I <sub>D</sub> =6A	-	22	-	S
<b>Dynamic Characteristics</b>						
IPECNut capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V f=1.0MHz	-	370	-	pF
Output capacitance	C <sub>OSS</sub>		-	65	-	
Reverse transfer capacitance	C <sub>RSS</sub>		-	40	-	
<b>Switching Characteristics</b>						
Turn-on delay time	t <sub>D(ON)</sub>	V <sub>DS</sub> =15V V <sub>GS</sub> =10V R <sub>L</sub> =2.6 ohm R <sub>GEN</sub> =3ohm	-	4.5	-	ns
Rise time	t <sub>r</sub>		-	2.5	-	
Turn-off delay time	t <sub>D(OFF)</sub>		-	14.5	-	
Fall time	t <sub>f</sub>		-	2.5	-	
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =6A V <sub>GS</sub> =10V	-	7.1	-	nC
Gate-source charge	Q <sub>gs</sub>		-	1.4	-	
Gate-drain charge	Q <sub>gd</sub>		-	1.7	-	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =1A	-	0.82	1.16	V

**Thermal Characteristics**

Parameter		Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient <sup>A</sup>	≤ 10s	R <sub>θJA</sub>	65	90	°C/W
Maximum Junction-to-Ambient <sup>A</sup>	Steady-State		85	125	
Maximum Junction-to-Lead <sup>B</sup>	Steady-State		63	80	

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

## Typical Performance Characteristics

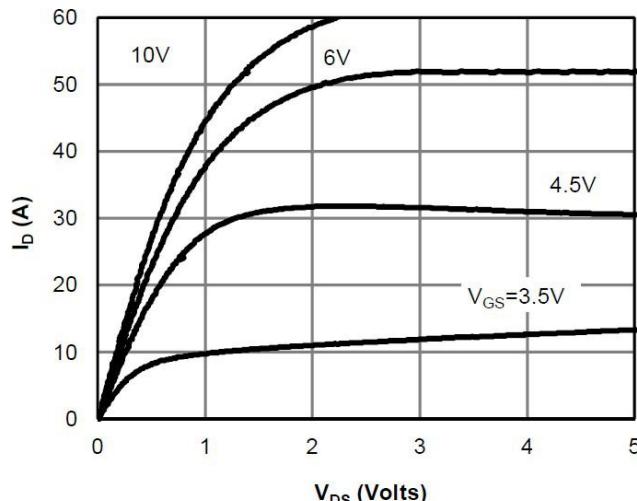


Figure 1: On-Region Characteristics

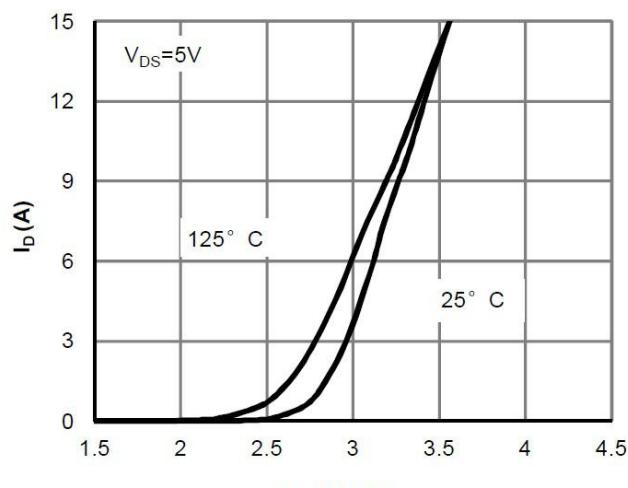


Figure 2: Transfer Characteristics

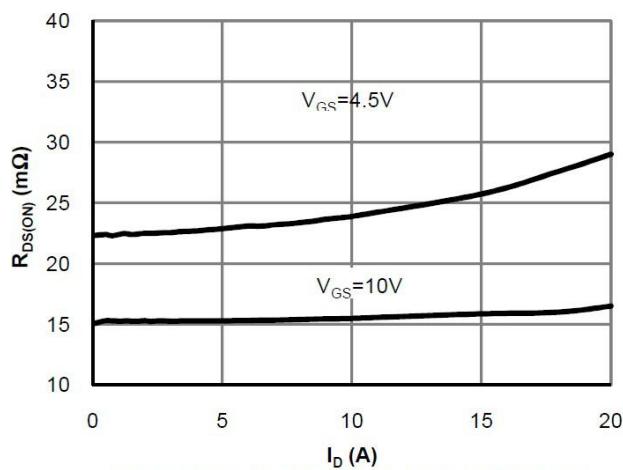


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

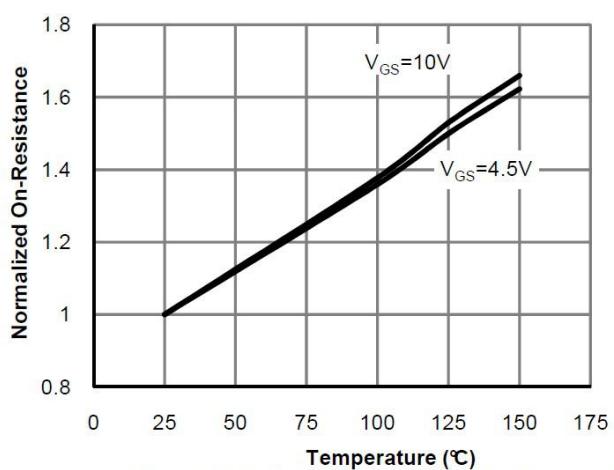


Figure 4: On-Resistance vs. Junction Temperature

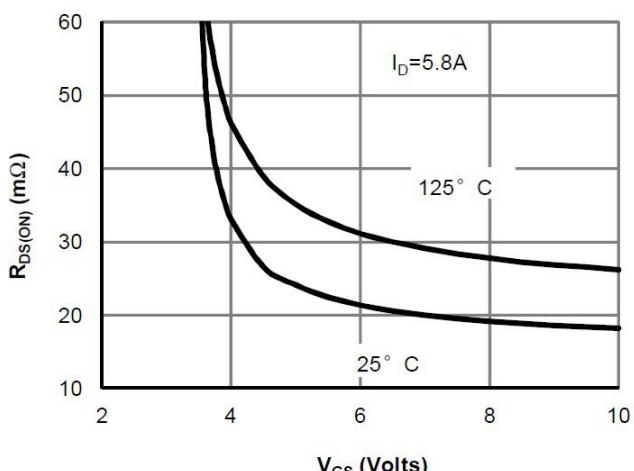


Figure 5: On-Resistance vs. Gate-Source Voltage

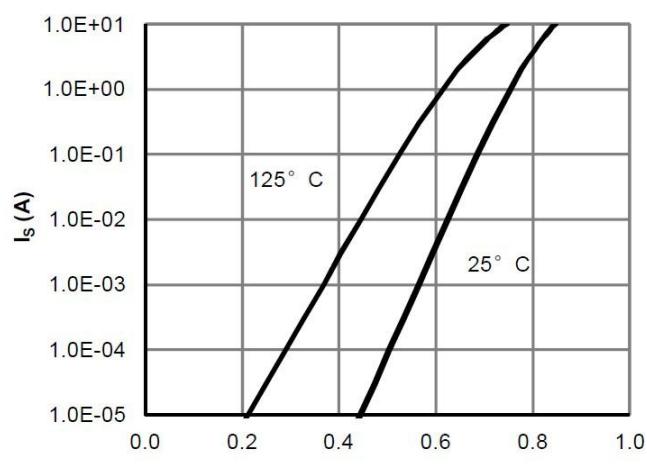


Figure 6: Body-Diode Characteristics

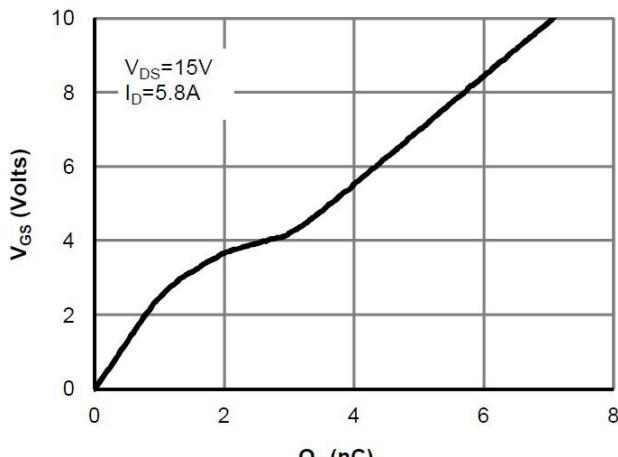


Figure 7: Gate-Charge Characteristics

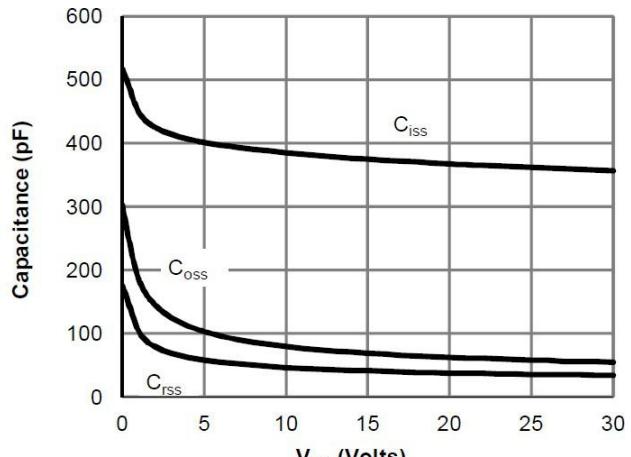


Figure 8: Capacitance Characteristics

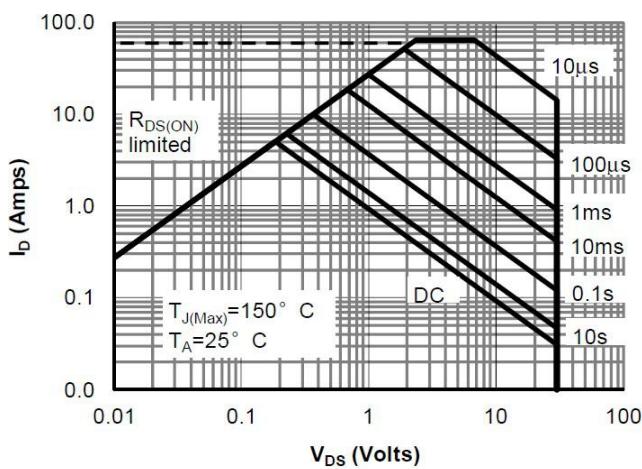


Figure 9: Maximum Forward Biased Safe Operating Area

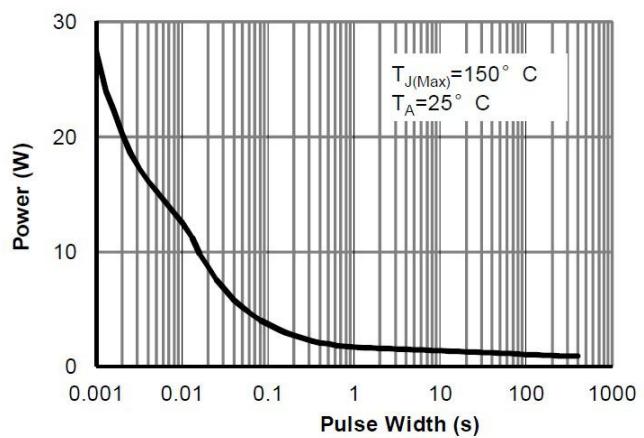


Figure 10: Single Pulse Power Rating Junction-to-Ambient

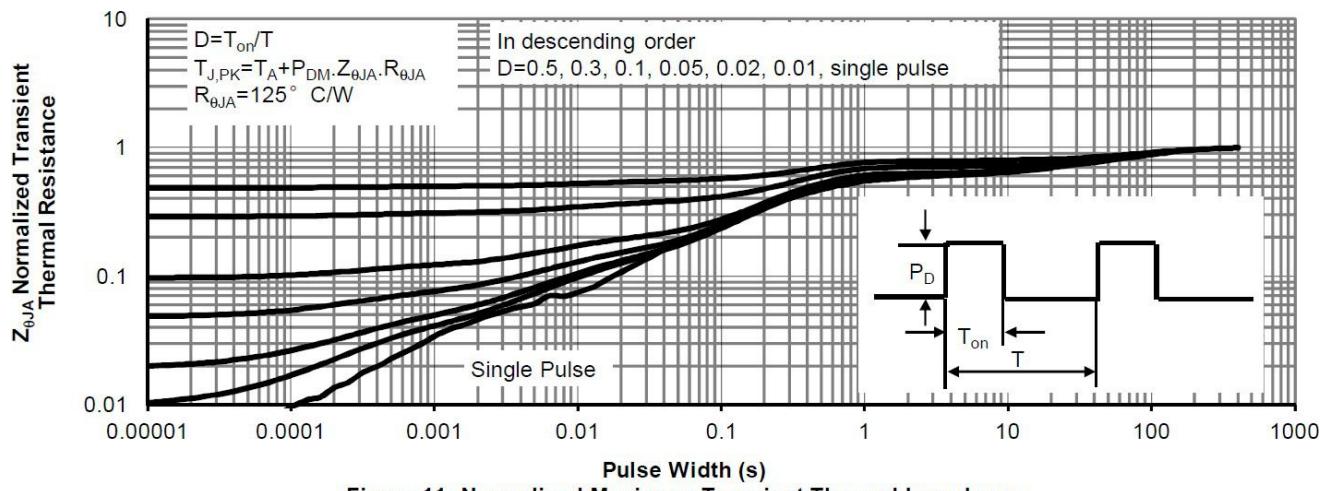
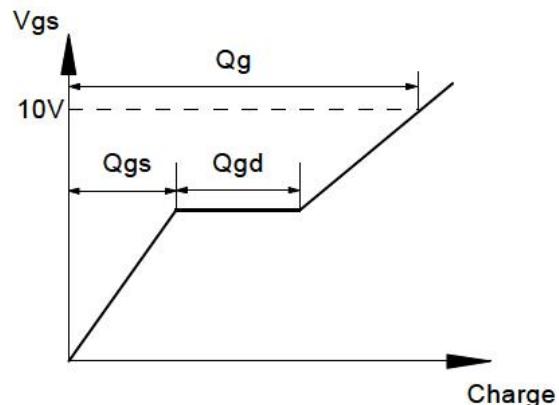
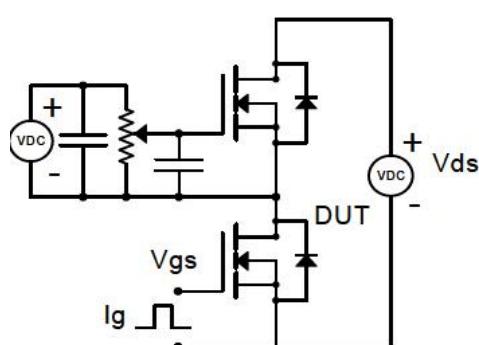


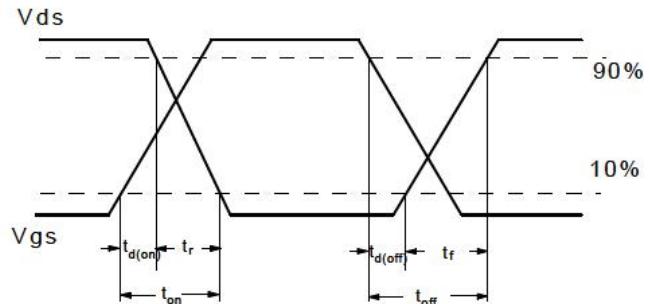
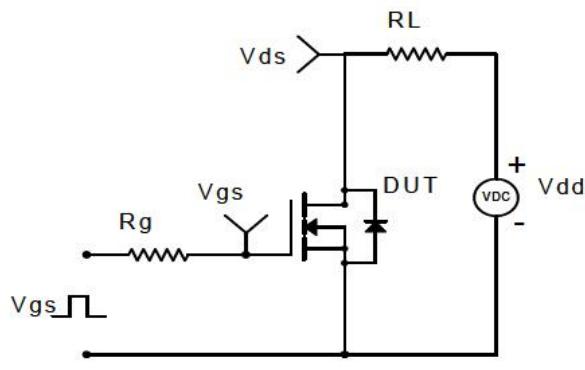
Figure 11: Normalized Maximum Transient Thermal Impedance

## Gate Charge Test Circuit & Waveform

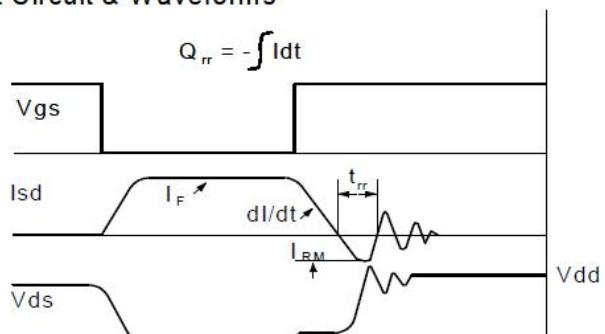
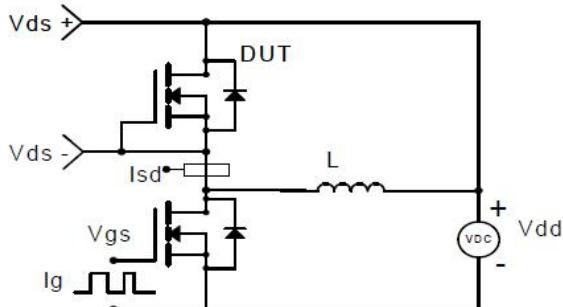


## Resistive Switching Test Circuit & Waveforms

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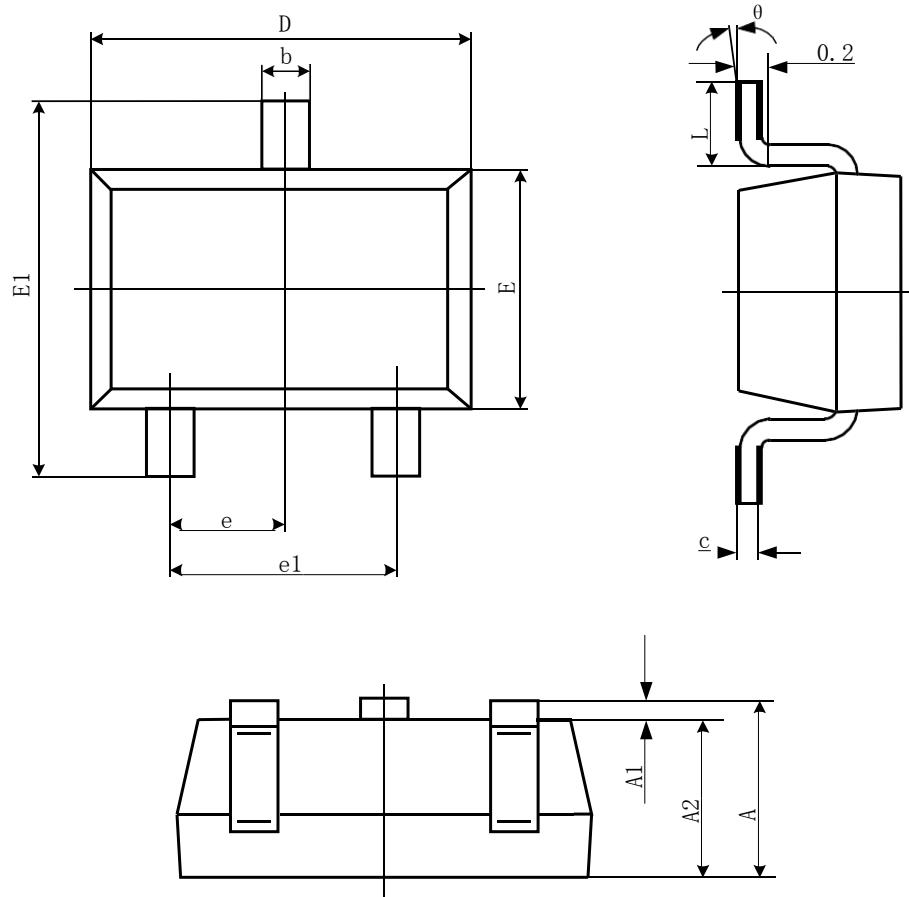


## Diode Recovery Test Circuit & Waveforms



## Package Information

- SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
$\theta$	0°	8°	0°	8°